

Title (en)  
Sensor assembly

Title (de)  
Sensoranordnung

Title (fr)  
Dispositif de détection

Publication  
**EP 2704544 A3 20150114 (DE)**

Application  
**EP 13178922 A 20130801**

Priority  
DE 102012108147 A 20120903

Abstract (en)  
[origin: EP2704544A2] The arrangement (10) has a mounted board (11) provided with electrical terminals, and an electronic component (13) arranged on the mounted board. A housing (14) is made of thermoplastic material whose inner space (15) is arranged at an end section of the mounted board. A transformed portion of the housing is provided on the electrical terminals of the mounted board facing a side of the housing. The transformed portion rests against the mounted board, where the sensor arrangement is encapsulated in a range from the transformed portion of the housing to a connection cable (19). An independent claim is also included for a method for manufacturing a sensor arrangement.

IPC 8 full level  
**H05K 5/06** (2006.01); **G01D 11/24** (2006.01); **G01P 1/02** (2006.01); **H03K 17/95** (2006.01)

CPC (source: EP)  
**G01D 11/245** (2013.01); **G01P 1/02** (2013.01); **H05K 5/065** (2013.01); **H05K 5/069** (2013.01)

Citation (search report)

- [A] DE 102009060872 A1 20110818 - BAUMER INNOTECH AG [CH]
- [A] DE 2952297 A1 19810702 - SCHALLER WERNER DIPL ING
- [A] DE 19504608 A1 19960814 - BALLUFF GEBHARD FEINMECH [DE]
- [A] DE 10121776 A1 20021128 - SICK AG [DE]

Cited by  
DE102015217572B3; DE102015217576A1; US10506732B2; US10470325B2

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**EP 2704544 A2 20140305; EP 2704544 A3 20150114; EP 2704544 B1 20160203**; DE 102012108147 A1 20140327

DOCDB simple family (application)  
**EP 13178922 A 20130801**; DE 102012108147 A 20120903